

N-Channel 40V MOSFET

Product summary

V_{DS} (V)	$R_{DS(on),max}$ (m Ω)	I_D (A)
40	1.4 @ $V_{GS} = 10V$	212 ⁽¹⁾

Features

- Low $R_{DS(on)}$ trench technology
- Low thermal impedance
- Fast switching speed
- 100% avalanche tested

Applications

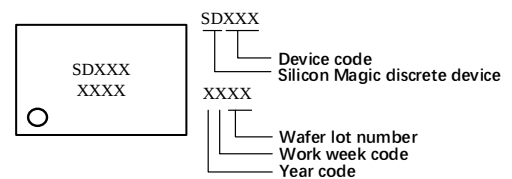
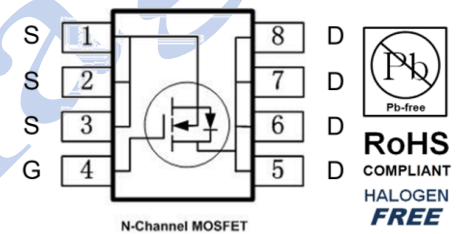
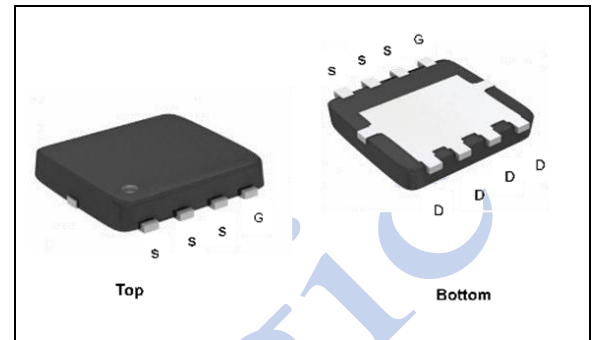
- DC/DC conversion
- Power switch
- Motor drives

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Package and ordering information

Ordering code	Package	Device code
SDH04N1P4C-AA	PDFN5*6-8L	AGS

DFN5*6-8L



1. Maximum ratings

Absolute maximum ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)				
Parameter		Symbol	Limit	Unit
Drain-source voltage		V_{DS}	40	V
Gate-source voltage		V_{GS}	± 20	
Continuous drain current	$T_C = 25^\circ\text{C}$ ⁽¹⁾	I_D	212	A
	$T_C = 100^\circ\text{C}$		134	
	$T_A = 25^\circ\text{C}$ ⁽⁴⁾		34	
Pulsed drain current ⁽²⁾		$I_{D,pulse}$	849	
Avalanche energy, single pulse ⁽³⁾		E_{AS}	521	mJ
Power dissipation	$T_C = 25^\circ\text{C}$	P_D	104	W
	$T_A = 25^\circ\text{C}$ ⁽⁴⁾		2.7	
Operating junction and storage temperature range		T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

2. Thermal resistance ratings

Thermal resistance ratings						
Parameter		Symbol	Max.	Unit		
Thermal resistance, junction-to-case	Steady state	$R_{\theta JC}$	1.2	°C/W		
Thermal resistance, junction-to-ambient ⁽⁴⁾	Steady state	$R_{\theta JA}$	45			

3. Electrical Characteristics

Electrical characteristics (T _J = 25°C unless otherwise noted)						
Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Static parameter						
Drain to source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA	40			V
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2.2	3	3.8	V
Gate-body leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V			1	μA
Drain-source on-resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 50 A		1.1	1.4	mΩ
Forward transconductance ⁽⁵⁾	g _{fs}	V _{DS} = 5 V, I _D = 50 A		180		S
Gate resistance	R _g	f = 1 MHz		3		Ω
Dynamic ⁽⁵⁾						
Total gate charge	Q _g	V _{DS} = 20 V, I _D = 50 A, V _{GS} = 10 V		46		nC
Gate-source charge	Q _{gs}			17		
Gate-drain charge	Q _{gd}			8.5		
Turn-on delay time	t _{d(on)}	V _{DS} = 20 V, I _D = 50 A, V _{GS} = 10 V, R _{GEN} = 4.7 Ω		43		ns
Rise time	t _r			108		
Turn-off delay time	t _{d(off)}			54		
Fall time	t _f			25		
Input capacitance	C _{iss}	V _{DS} = 20 V, V _{GS} = 0 V, f = 1 MHz		3520		pF
Output capacitance	C _{oss}			1630		
Reverse transfer capacitance	C _{rss}			63		
Reverse Diode Characteristics ⁽⁵⁾						
Diode forward voltage	V _{SD}	V _{GS} = 0 V, I _F = 50 A		0.8	1.1	V
Reverse recovery time	t _{rr}	V _{DS} = 20 V, I _F = 50 A, di/dt = 100 A/μs		49		ns
Reverse recovery charge	Q _{rr}			43		nC

Notes

- (1) Limited by maximum junction temperature.
- (2) Pulse width limited by maximum junction temperature.
- (3) $V_{DS} = 40\text{ V}, V_{GS} = 10\text{ V}, L = 0.3\text{ mH}$.
- (4) $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5x1.5 in. board of FR-4 material.
- (5) Guaranteed by design, not subject to production testing.

4. Electrical characteristics diagrams

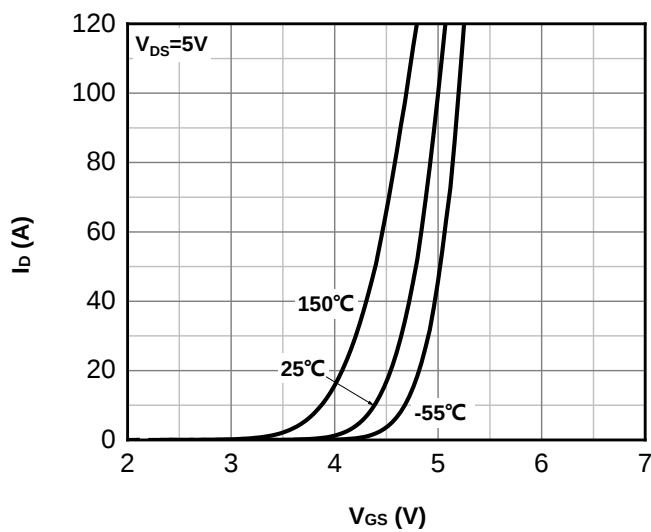
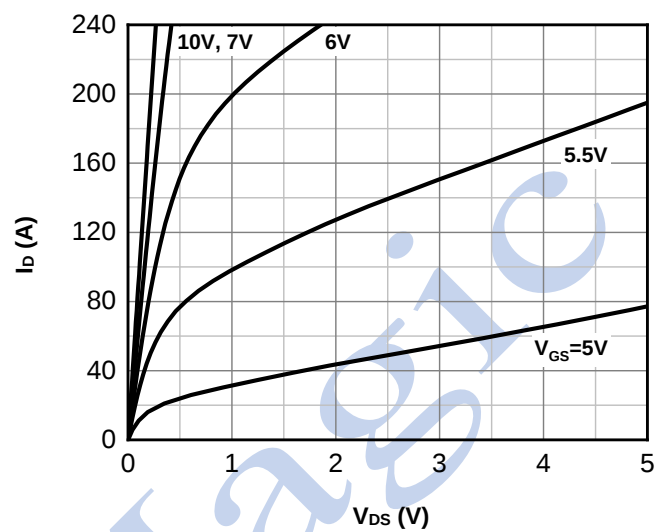
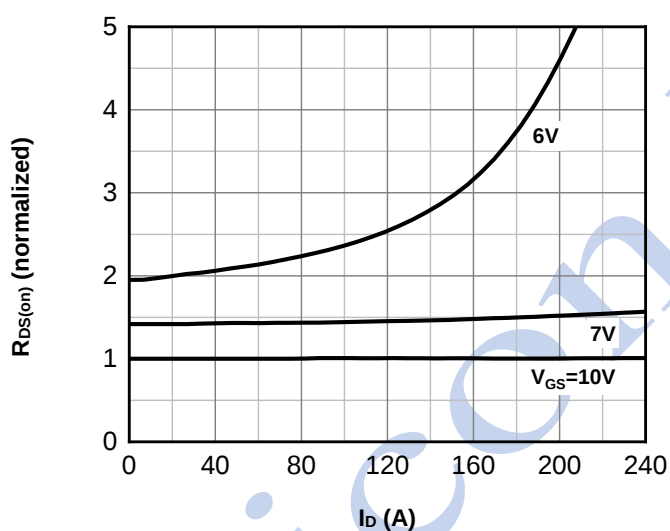
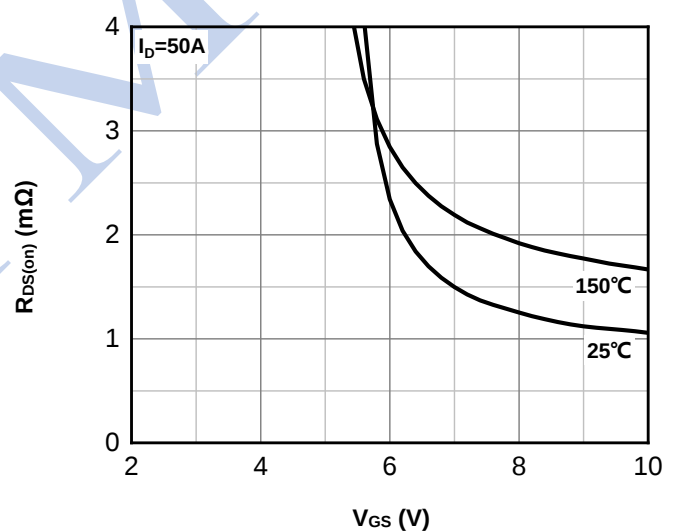
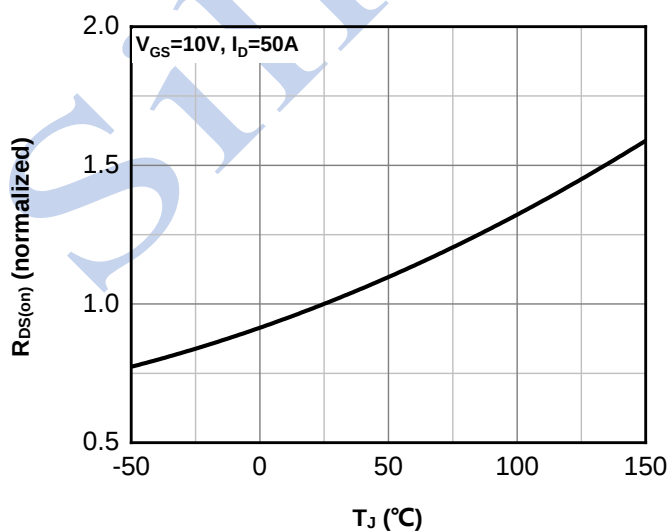
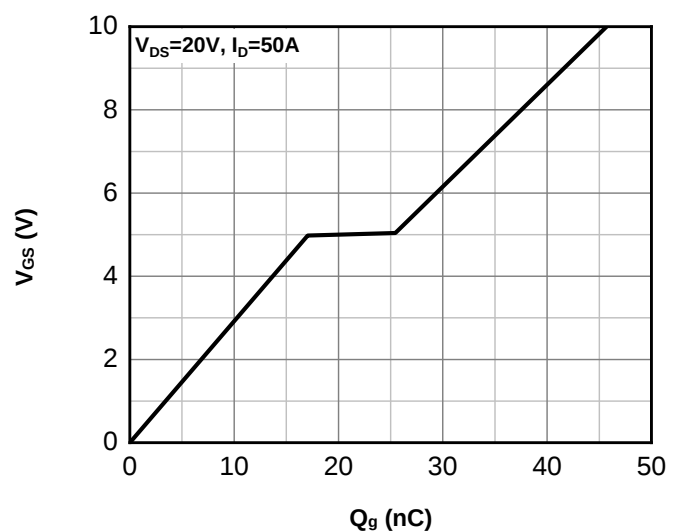
Fig.1 Typ. transfer characteristics

Fig.2 Typ. output characteristics

Fig.3 Normalized on-resistance vs drain current

Fig.4 Typ. on-resistance vs gate-source voltage

Fig.5 Normalized on-resistance vs junction temperature

Fig.6 Typ. gate charge


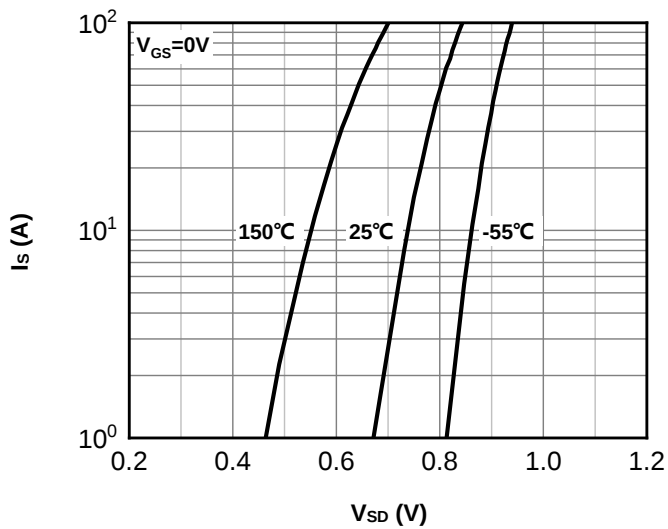
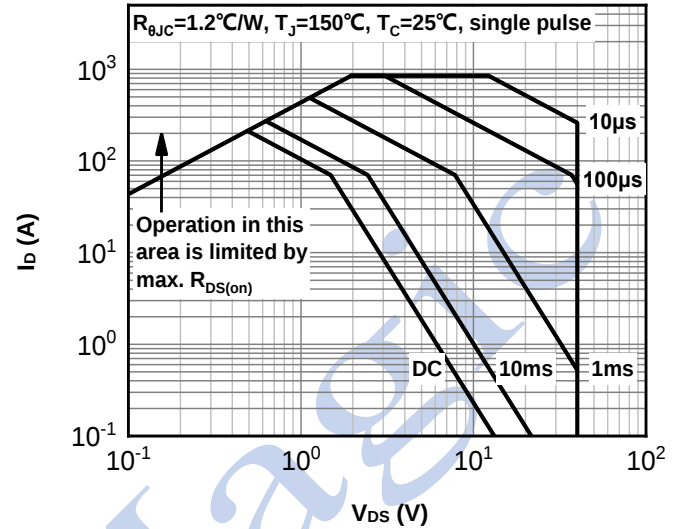
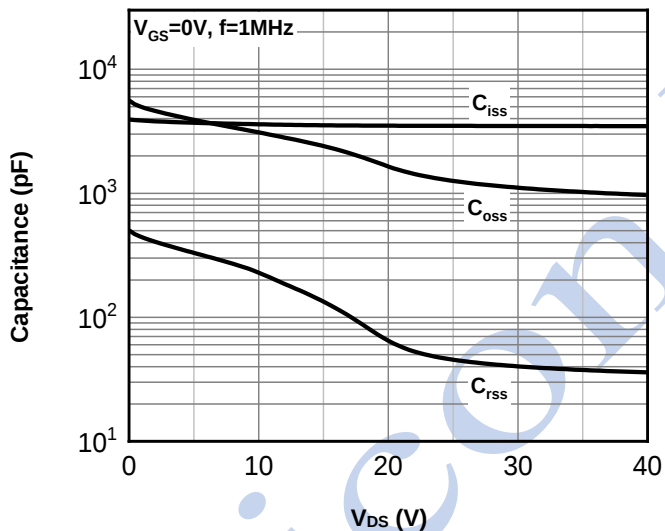
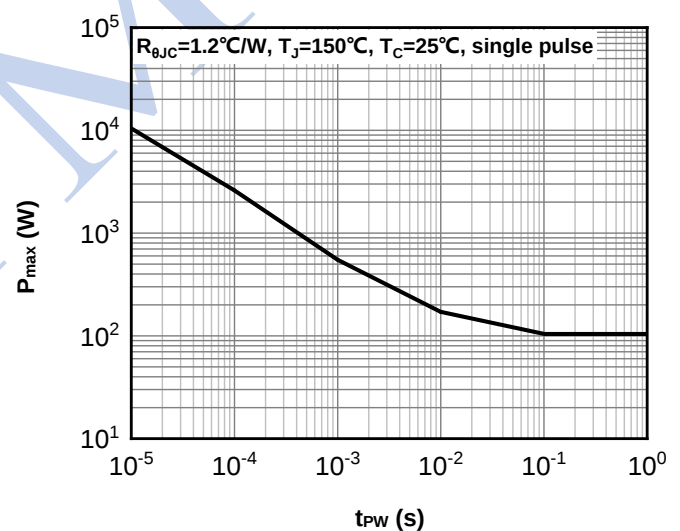
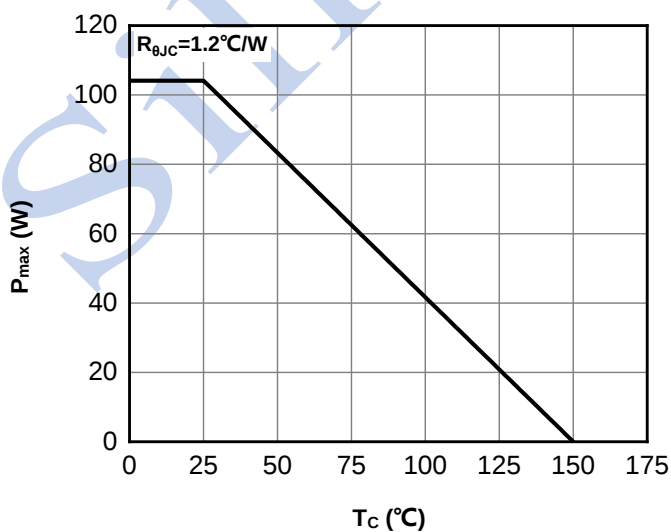
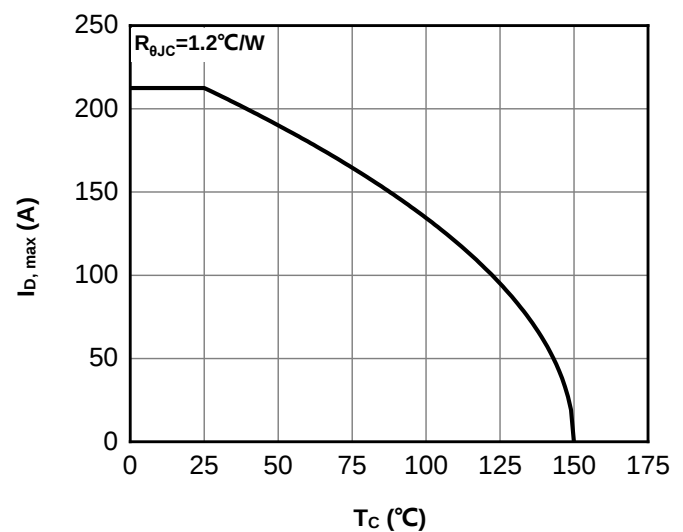
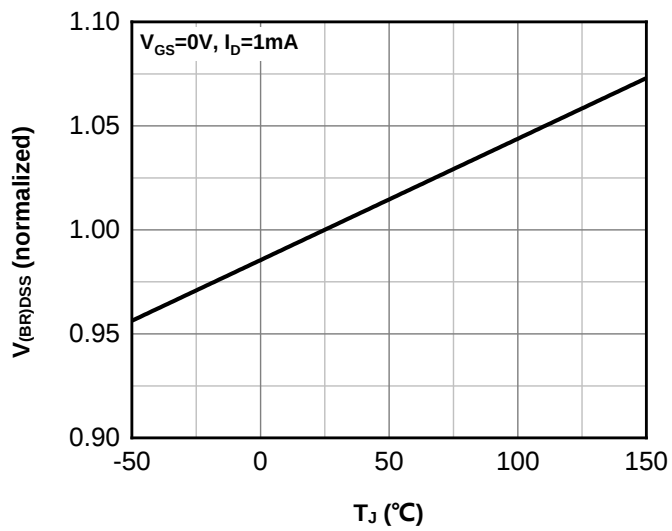
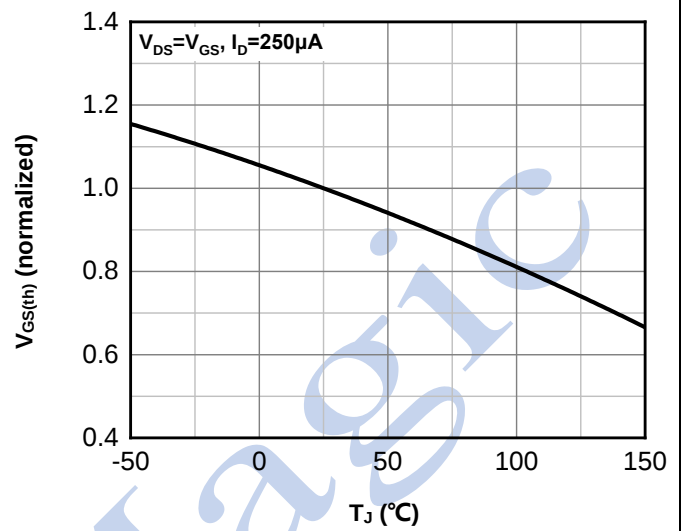
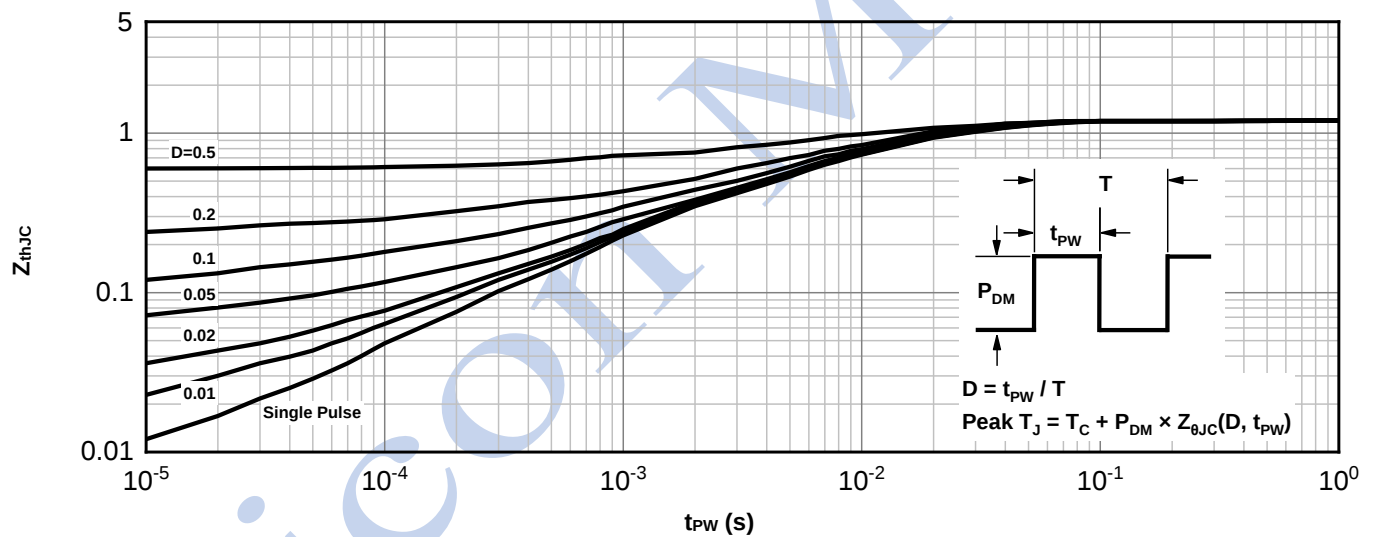
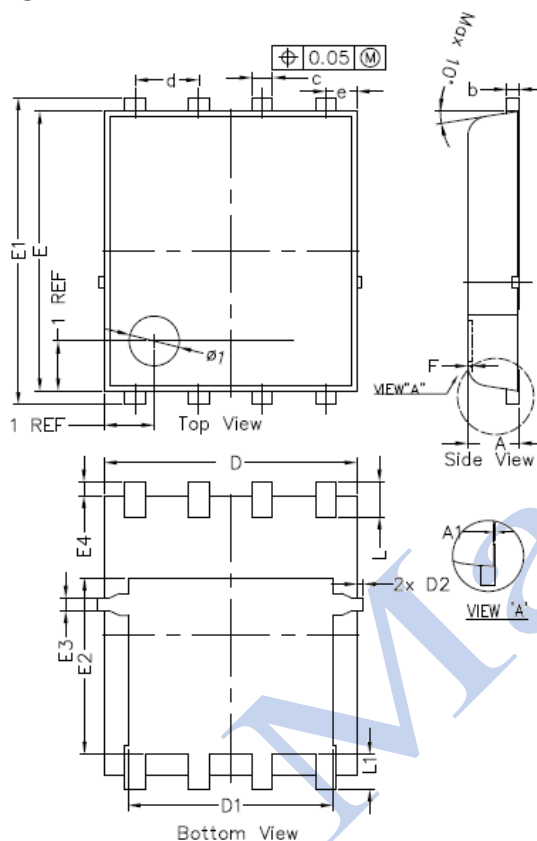
Fig.7 Typ. forward characteristics of body diode

Fig.8 Safe operating area

Fig.9 Typ. Capacitance

Fig.10 Single pulse maximum power dissipation

Fig.11 Max. power dissipation vs case temperature

Fig.12 Max. continuous drain current vs case temperature


Fig.13 Normalized $V_{(BR)DSS}$ vs junction temperature

Fig.14 Normalized $V_{GS(th)}$ vs junction temperature

Fig.15 Transient thermal impedance from junction to case


5. Package outline dimensions



Dim	Millimeters		
	Min	Nom	Max
A	0.900	1.000	1.100
A1	0.000	---	0.050
b	0.246	0.254	0.312
c	0.310	0.410	0.510
d	1.27BSC		
D	4.950	5.050	5.150
D1	4.000	4.100	4.200
D2	---	---	0.125
e	0.62BSC		
E	5.500	5.600	5.700
E1	6.050	6.150	6.250
E2	3.425	3.525	3.625
E3	0.150	0.250	0.350
E4	0.175	0.275	0.375
F	---	---	0.100
L	0.500	0.600	0.700
L1	0.600	0.700	0.800

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